

## 2SA2161J

### Silicon PNP epitaxial planar type

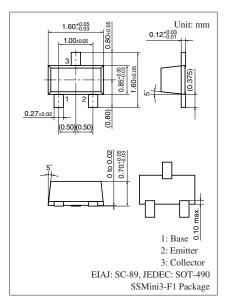
For general amplification Complementary to 2SC6037J

#### ■ Features

- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- SS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-15	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-12	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	-5	V	
Collector current	$I_C$	-500	mA	
Peak collector current	$I_{CP}$	-1	A	
Collector power dissipation	P <sub>C</sub>	125	mW	
Junction temperature	$T_{j}$	125	°C	
Storage temperature	$T_{stg}$	-55 to +125	°C	



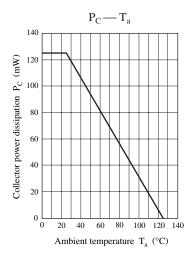
Marking Symbol: 2U

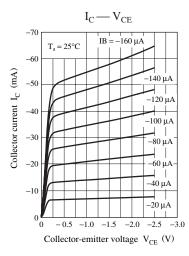
#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

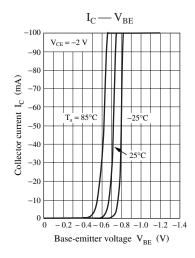
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = -10 \ \mu A, I_E = 0$	-15			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = -1 \text{ mA}, I_B = 0$	-12			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = -10 \ \mu A, I_C = 0$	-5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -15 \text{ V}, I_E = 0$			- 0.1	μΑ
Forward current transfer ratio	h <sub>FE</sub>	$V_{CE} = -2 \text{ V}, I_{C} = -10 \text{ mA}$	270		680	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = -200 \text{ mA}, I_B = -10 \text{ mA}$			-250	mV
Transition frequency	$f_T$	$V_{CB} = -2 \text{ V}, I_E = 10 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		4.5		pF
(Common base, input open circuited)						

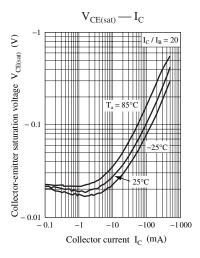
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

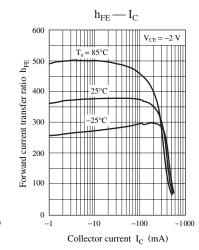
### **Panasonic**

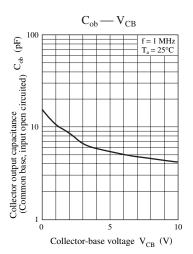












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